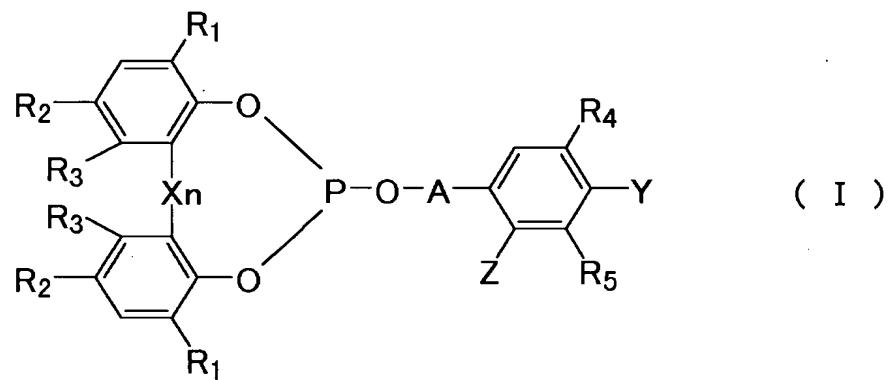


ABSTRACT OF THE DISCLOSURE

A polypropylene resin composition for a film for metallization, which comprises 100 parts by weight of a 5 polypropylene resin and 0.01 to 1 part by weight of a phosphite represented by the general formula (I):



(wherein, R¹, R², R⁴ and R⁵ represent individually hydrogen, an alkyl, cycloalkyl, alkylcycloalkyl, aralkyl or phenyl; R³ 10 represents hydrogen or an alkyl; X represents sulfur atom or a -CHR⁶- group (R⁶ represents hydrogen, an alkyl or cycloalkyl); n is 0 or 1; A is an alkylene or a *-CO(R⁷)_m-group (R⁷ is an alkylene, * mark is indicative of the bonding site of A to oxygen and m is 0 or 1); and either one of Y or 15 Z is hydroxy, alkoxy or aralkyloxy and the other is hydrogen or an alkyl.), a film thereof, and a metallized film thereof.